

1 7. (Amended) The method of claim 6, further comprising attaching a solder ball
2 to the substrate.

1 8. (Amended) The method of claim 5, further comprising molding an
2 encapsulant onto the substrate and the integrated circuit.

1 9. A method for assembling an integrated circuit package, comprising:
2 applying an epoxy to a thermal element;
3 placing the epoxy and the thermal element onto an integrated circuit; and,
4 curing the epoxy with energy at a microwave frequency.

1 10. (Amended) The method of claim 9, further comprising mounting the
2 integrated circuit to a substrate.

1 11. (Amended) The method of claim 10, further comprising attaching a solder ball
2 to the substrate.

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1 12. (Amended) The method of claim 9, further comprising molding an
2 encapsulant onto the substrate and the integrated circuit.

1 13. The method of claim 5, wherein said thermal element is a heat spreader.

1 14. The method of claim 5, wherein prior to applying said epoxy, the method
2 further comprises providing a thermally conductive filler to a resin to form said epoxy.

1 15. The method of claim 14, wherein said thermally conductive filler includes
2 carbon particles.

1 16. The method of claim 5, wherein said placing of said thermal element includes
2 attaching said thermal element to said epoxy.

1 17. The method of claim 5, wherein said curing of the epoxy includes

2 selecting the microwave frequency to cure the epoxy without damaging the integrated
3 circuit or heating other components within the integrated circuit package; and
4 generating energy at the microwave frequency by a microwave generator directed
5 toward the epoxy.

1 18. The method of claim 9, wherein prior to applying said epoxy to the thermal
2 element, the method further comprises providing a thermally conductive filler to a resin to
3 form said epoxy.

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cancel 1 19. The method of claim 10 further comprising baking the substrate before curing
2 the epoxy.

1 20. The method of claim 9, wherein said curing of the epoxy includes
2 selecting the microwave frequency to cure the epoxy without damaging the integrated
3 circuit or heating other components within the integrated circuit package; and
4 generating energy at the microwave frequency by a microwave generator directed
5 toward the epoxy.